

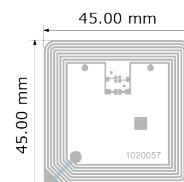
**IC Specifications**

- IC Protocol: ISO/IEC 15693
- ISO Typical Frequency: 13.56 MHz
- Chip: NXP I CODE SLIX
- User Memory: 896bit

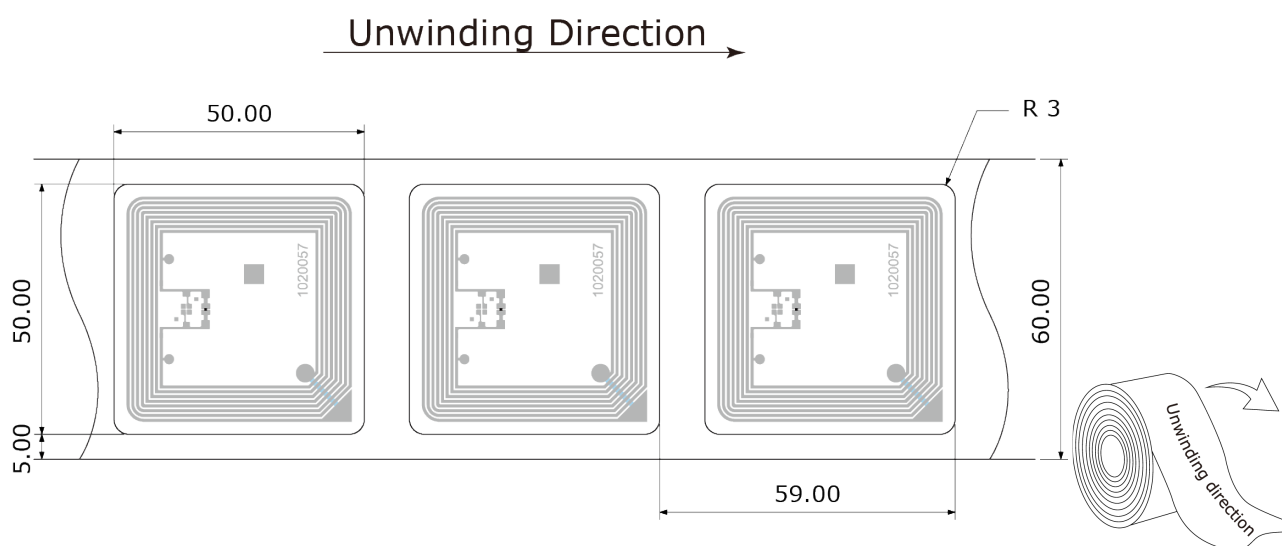
- Chip Part No.: SL2S2002FUD/12NC
- Operating Temperature: -40°C/+85°C
- Storage Temperature: -55°C/+125°C
- Chip Capacitor: 23.5PF

**Antenna Design**

Top: Aluminum/30 μm  
 Substrate: PET/38 μm  
 Bottom: Aluminum/10 μm



**Layout and Dimensions (mm)**



**Construction (Thickness: mm ; Total: +/- 10%)**

0.072		Paper with adhesive(04/RP5X/01/HO)
0.085		Inlay
0.04		Hot melt adhesive(DT3981)
0.055		Silicon Paper(04/RP5X/01/HO)

**Product Parameter**

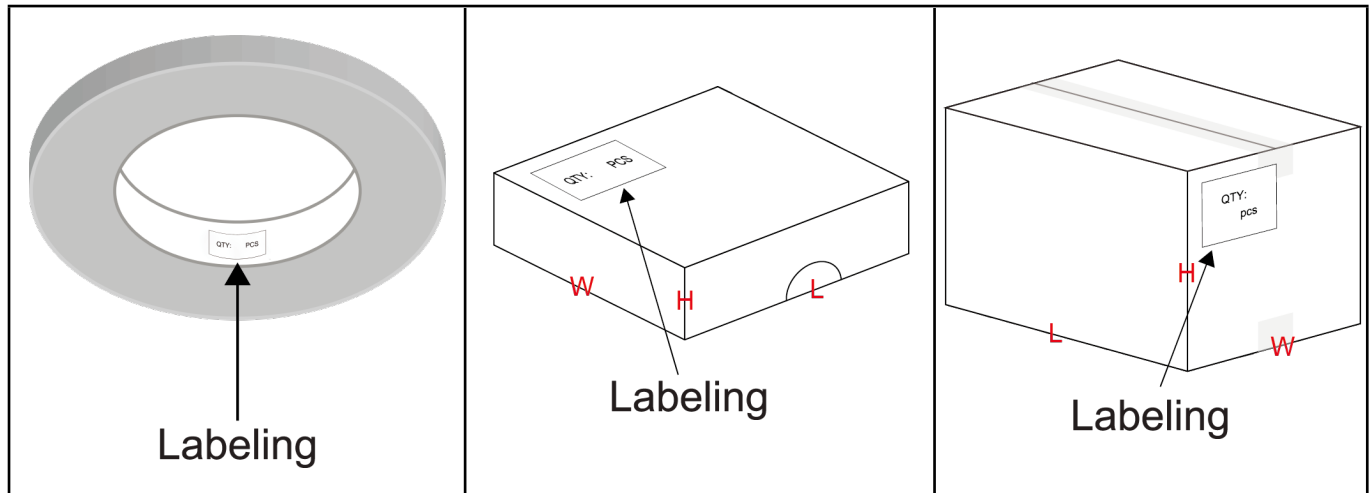
Parameters	Characteristics
Tail	1 m leading silicon paper at the beginning and ending of roll
Defectives	NA.
Yield	≥ 99 %

**Package information**

**Size** (TBD)

Core internal Diameter: <u>76.2</u> ± <u>1</u> mm Core Thickness: <u>6</u> ±1mm Quantity / Roll: <u>1000</u> pcs Total	- 1 roll/inner case  Length: <u>160</u> mm Width : <u>160</u> mm Height: <u>60</u> mm	- <u>10</u> inner /master ctn  Length: <u>370</u> mm Width : <u>180</u> mm Height: <u>350</u> mm
Roll External Diameter: ≤ <u>160</u> mm Joints: Below 2 times joints per roll(excluding 2 leading joints) Crystal Clear Tape(PP-030) ,the width is 24 mm		

**Illustration**



**Labeling information**

<div style="border: 1px solid black; padding: 10px; text-align: center;"> <p><b>QTY: PCS</b></p> </div> <p>colour:white 1pcs/roll size:70*30 mm</p>	<div style="border: 1px solid black; padding: 10px; text-align: center;"> <p><b>QTY: PCS</b></p> </div> <p>colour:white 1pcs/inner case size:70*30 mm</p>	<div style="border: 1px solid black; padding: 10px; text-align: center;"> <p><b>QTY: pcs</b></p> </div> <p>colour:white 1pcs/master ctn size:100*80 mm</p>
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**Others**